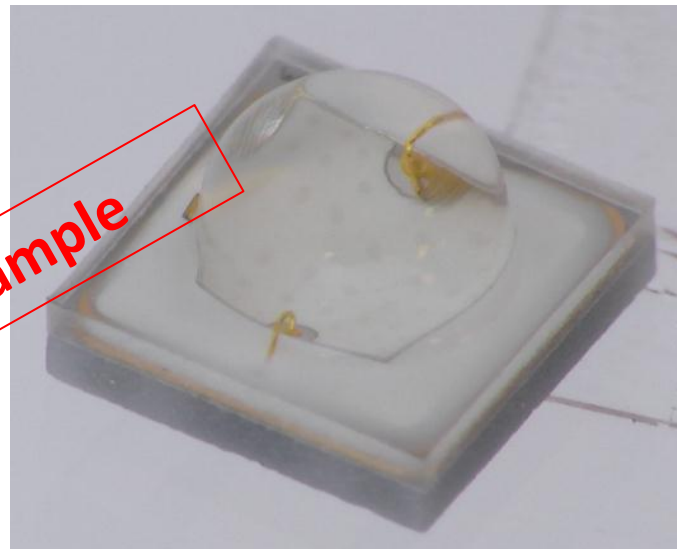
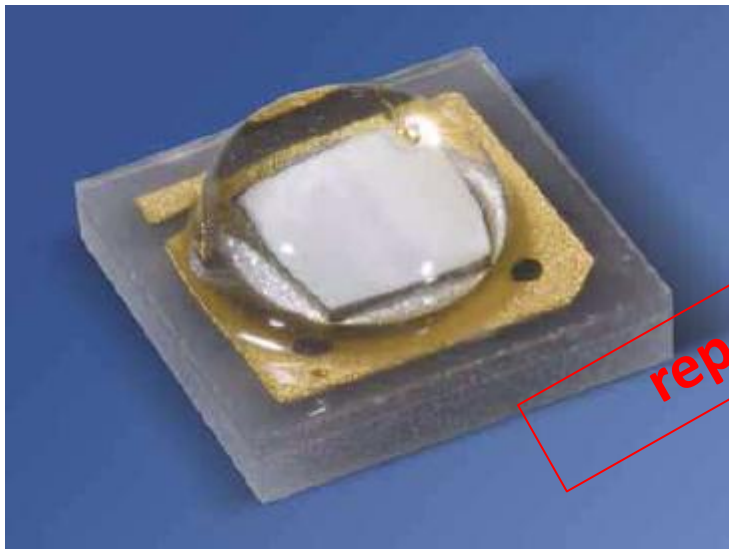


Reverse Costing analysis



OSRAM

**Oslon SSL and Square Royal Blue LED
1mm² LD-CQDP and 2mm² LD-CQAR**

February 2013 - Version 1

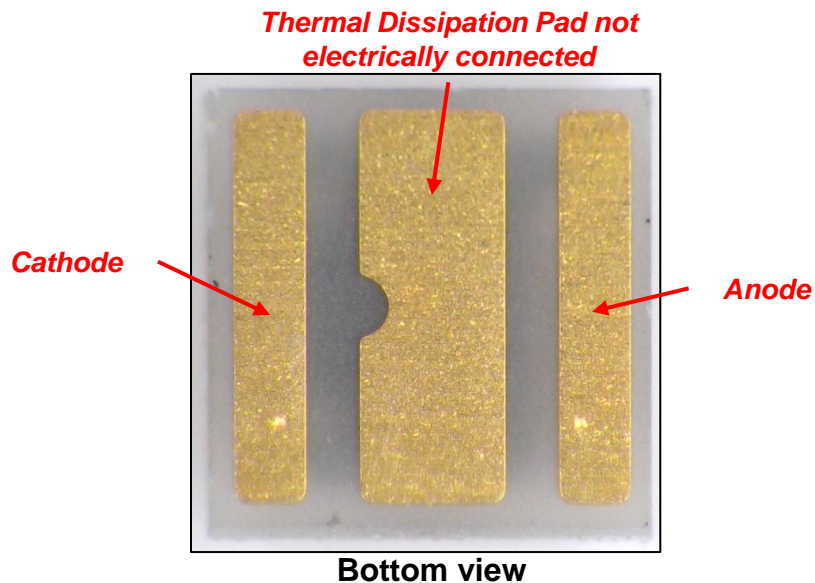
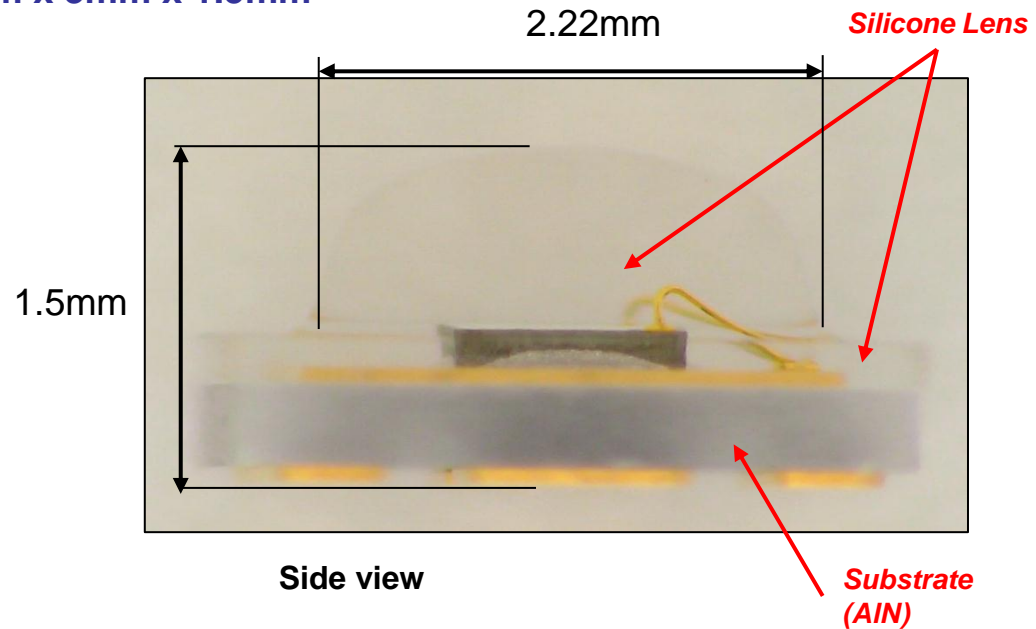
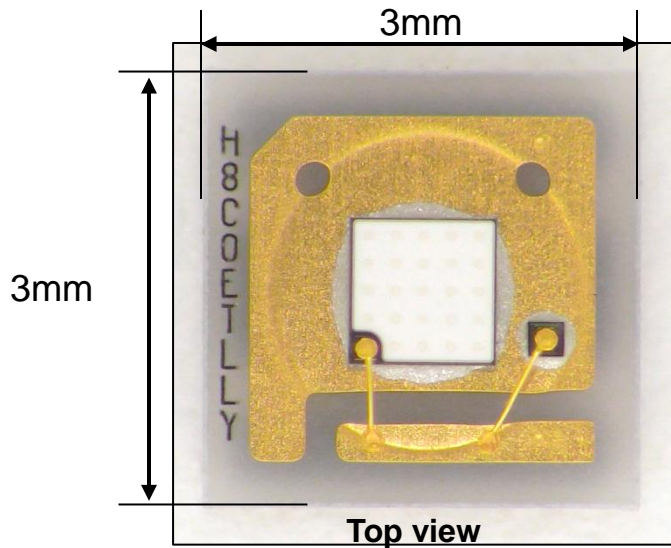
Written by: Sylvain HALLEREAU

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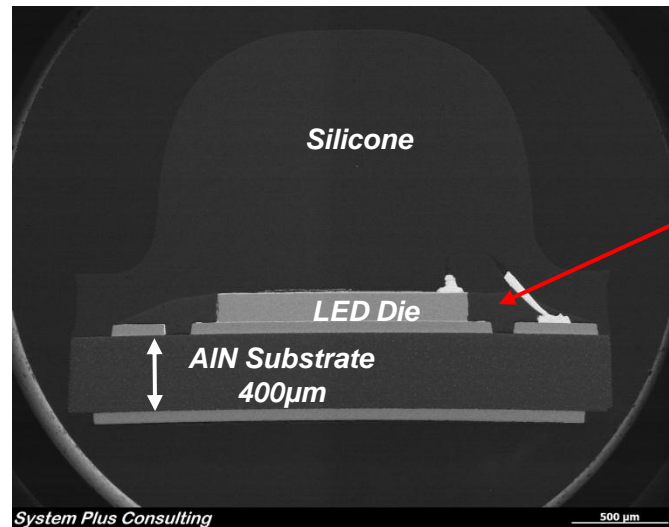
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- **This full reverse costing study has been conducted to provide insight on technology data, manufacturing cost and selling price of 2 OSRAM Oslon Blue LEDs:**
 - ✓ **SSL** ref. LD-CQDP
 - ✓ **Square** ref. LD-CQAR
- **The LD CQDP series have a typical Luminous Flux of 515 mW at 350 mA and up to 1219 mW at 1 A. The semiconductor LED area measures 1mm sq.**
- **The LD-CQAR series have a typical Luminous Flux of 1100mW at 700 mA. The semiconductor LED area measures 2mm sq.**
- **The components are provided in a specific 2-pins package, compatible with SMT process.**
- **They can be used in a wide range of lighting applications, including:**
 - ✓ Architectural lighting
 - ✓ Stage and entertainment lighting
 - ✓ Retail and shop lighting
 - ✓ Color changing fixtures
 - ✓ Remote-phosphor fixtures

- The package is a specific 2-pins package, 3mm x 3mm x 1.5mm



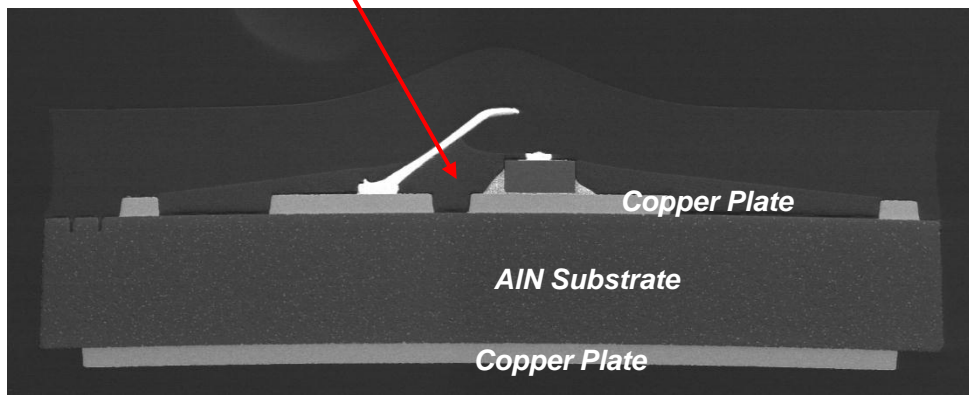
- The package is a lead-less ceramic carrier, with an over molded one piece silicone lens. The LED die and protection diode sit on top of a copper plate. Two bond wires are present: one connecting to the LED die and one to the protection diode.



Cross-section view

White silicone

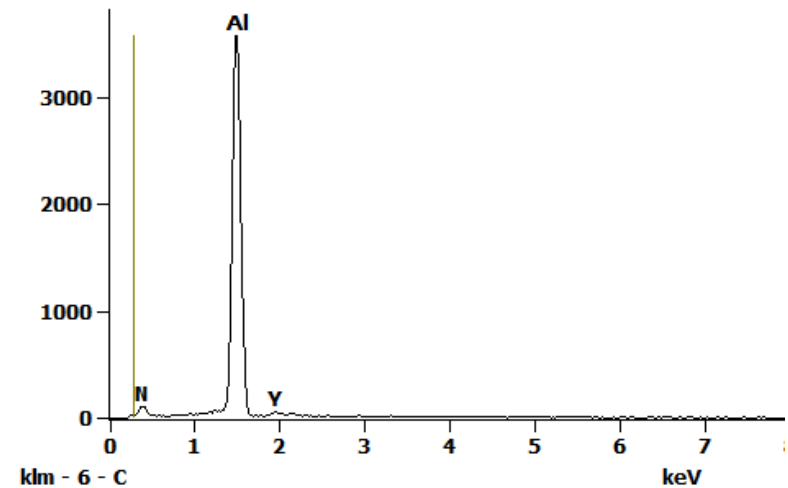
The white silicone has partially covered the protection diode.



Cross-section view

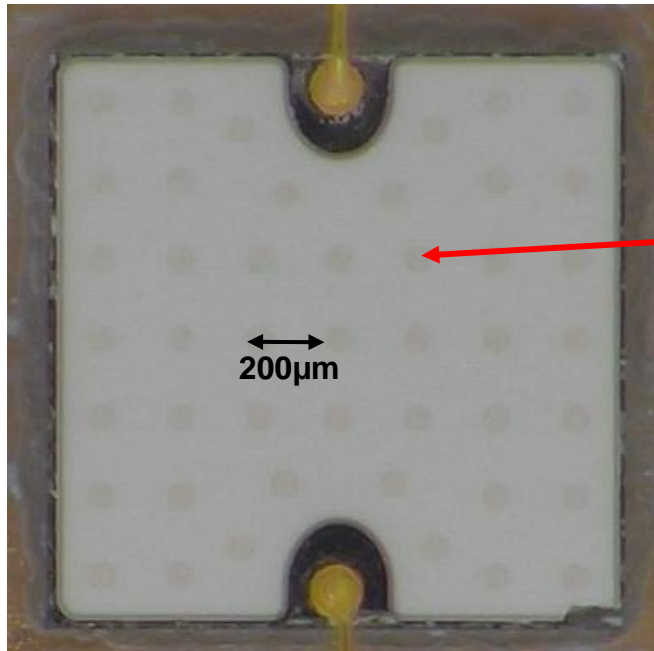
Full scale counts: 3565

Coupe 1 - MEB (15)_pt1



EDX spectrum of the ceramic package

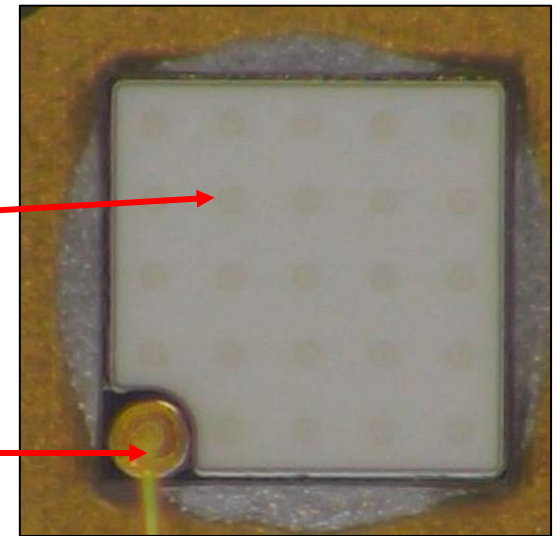
- The ceramic package is an AlN ceramic substrate with a small percentage of yttrium, conventional additive in the manufacture of AlN ceramics.



2mm² LED

The GaN layer is white on the pictures.

Cathode contact



Anode

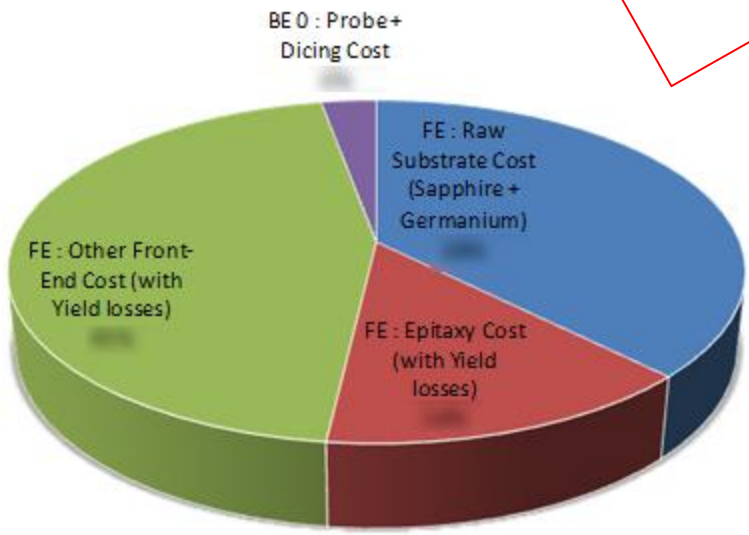
1mm² LED

- UX:3 technology : the cathode is under the GaN layer.
- The new design of the cathode and anode enhances the electron flux on all the surface of the LED without masking the light.
- We measure a pitch of 200µm between each cathode contact

	Low Yield		Medium Yield		High Yield	
	Cost	Breakdown	Cost	Breakdown	Cost	Breakdown
FE : Raw Substrate Cost (Sapphire + Germanium)						
FE : Epitaxy Cost (with Yield losses)						
FE : Other Front-End Cost (with Yield losses)						
BE 0 : Probe + Dicing Cost						
TOTAL Wafer Cost						
Nb of potential dies per wafer						
Nb of good dies per wafer						
FE : Raw Substrate Cost (Sapphire + Germanium)						
FE : Epitaxy Cost (with Yield losses)						
FE : Other Front-End Cost (with Yield losses)						
BE 0 : Probe + Dicing Cost						
Die Cost						

report sample - values blurred

Wafer Cost Breakdown



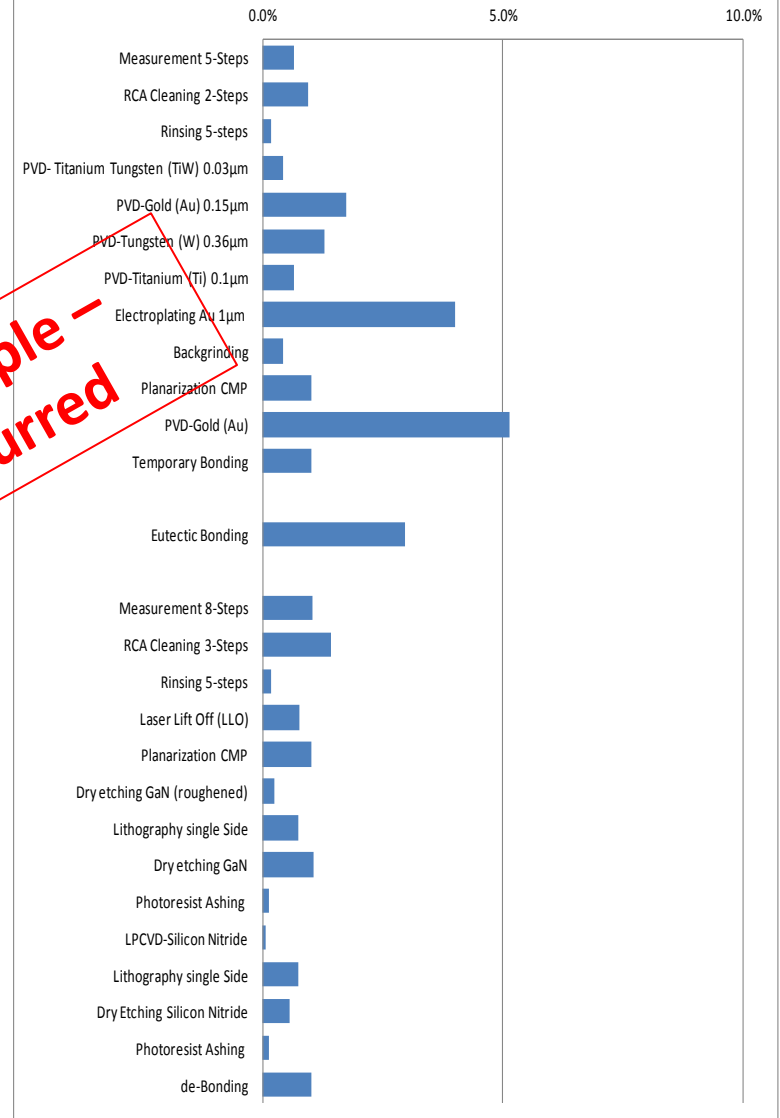
- The final wafer cost ranges from \$1,800 to \$1,870 according to yield variations.
- The final LED die cost ranges from \$0.18 to \$0.19 according to yield variations.
- The Front-End (FE) cost represents 99% (Substrate + Epitaxy + Other FE).
- The Back-End0 cost (Probe Test & Dicing) represents 1%.

Germanium Metal Layers

Measurement 5-Steps		
RCA Cleaning 2-Steps		
Rinsing 5-steps		
PVD- Titanium Tungsten (TiW) 0.03µm		
PVD-Gold (Au) 0.15µm		
PVD-Tungsten (W) 0.36µm		
PVD-Titanium (Ti) 0.1µm		
Electroplating Au 1µm		
Backgrinding		
Planarization CMP		
PVD-Gold (Au)		
Temporary Bonding		
Eutectic Bonding		
Front End on Germanium		
Measurement 8-Steps		
RCA Cleaning 3-Steps		
Rinsing 5-steps		
Laser Lift Off (LLO)		
Planarization CMP		
Dry etching GaN (roughened)		
Lithography single Side		
Dry etching GaN		
Photoresist Ashing		
LPCVD-Silicon Nitride		
Lithography single Side		
Dry Etching Silicon Nitride		
Photoresist Ashing		
de-Bonding		
TOTAL		

report sample - values blurred

Other FE Step Cost Breakdown (2/3)



- This reverse costing analysis represents the best cost/price evaluation given the publically available data, completed with industry expert estimates.
- These results are open for discussion. We can re-evaluate this circuit with your information. Please contact us:



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